



WDZB-RY型系列 无卤低烟阻燃聚烯烃绝缘软电线

WDZB-RY Flexible Wire of Flame-retardant halogen-free low-smoke polyolefine-insulated

FIRE AND HIGH TEMPERATURE RESISTANT HALOGEN-FREE LOW-SMOKE WIRES & CABLES 无卤低烟、耐火耐高温电线电缆系列

WDZB-RY 450/750V 1.5mm² SHANGHAI HANKE DIANXIAN YOUXIAN GONGSI

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应用范围

适用于高层建筑、地铁等人口密集场所,遇火灾时不释放卤化物等有毒气体。

APPLICATIONS

Intended for crowded places such as high rise buildings or subways where halogenide and other toxic gas emission is not allowed in case of fire.

电线结构

多股细裸束绞铜丝或镀锡铜丝导体;
无卤低烟阻燃型绝缘:
一般阻燃(WDZ-RY),B级阻燃(WDZB-RY),防鼠咬(WDZ-FSY-RY)。

WIRE MAKE-UP

Multi-stranded fine bare copper/tincopper conductor
Flame-retardant, halogen-free, low-smoke insulation
General flame retardance (WDZ-RY),
Level-B flame retardance (WDZB-RY),
Protection against gopher (WDZ-FSY-RY)

技术参数

温度范围: -5℃ ~ +90℃
额定电压: U₀/U 300/500V, 450/750V
符合标准: GB/T 19666-2005,GB/T 18380.3-2001
导体标准: GB/T 3956-1997 第5种

TECHNICAL DATA

Operating Temp.: -5℃ ~ +90℃
Rated Voltage: U₀/U 300/500V, 450/750V
Governing Std.: GB/T 19666-2005,GB/T 18380.3-2001
Conductor Std.: Category 5 in GB/T 3956-1997

导体截面 Cross Section mm ²	导体结构 Conductor Structure 根数/单根直径 Cond. No./O.D	标称外径 Nominal O.D. mm	最大外径 Max O.D. mm	重量(近似) Approx. Weight Kg/Km	导体20℃时 最大电阻 Max. Cond. R @ 20℃ ≤ (Ω/Km)	环境温度 30℃架空时 参考载流量(A) Ambient (aerial cable)
(WDZ-RY, WDZB-RY, WDZ-FSY-RY) 300/500V						
0.5	16/0.20	2.14	2.26	9.6	39.0	16
0.75	24/0.20	2.40	2.52	12.8	26.0	18
1	32/0.20	2.54	2.66	15.6	19.5	22
(WDZ-RY, WDZB-RY, WDZ-FSY-RY) 450/750V						
1.5	30/0.25	3.00	3.14	22.3	13.3	29
2.5	50/0.25	3.70	3.86	34.6	7.98	38
4	56/0.30	4.30	4.46	52.0	4.95	52
6	84/0.30	4.94	5.10	73.4	3.30	66
10	84/0.40	6.44	6.64	128	1.91	96
16	126/0.40	7.56	7.79	183	1.21	130
25	196/0.40	9.48	9.72	284	0.780	176
35	276/0.40	10.95	11.2	388	0.554	215
50	396/0.40	12.63	12.9	551	0.386	280
70	360/0.50	14.53	14.8	762	0.272	338

▲ 载流量是周围温度设定在30℃时的计算值。电线芯数、周围温度、布线状况等条件改变时应乘以系数。(见附录)

▲ Current-carrying capacity is the calculated value based on a ambient temperature of 30℃ and is to be multiplied by a factor when application conditions including number of cores, ambient temperature and wiring condition are changed. (see Appendix)